

IN THE SPECIFICATION:

Amend the specification as follows:

Paragraph beginning at page 1, line 11 has been amended as follows:

Q1 In a semiconductor device such as an IC for an automobile, there is a problematic unnecessary radiation as a noise emitted from circuits. In order to reduce the unnecessary radiation, a new method to solve the problem is ~~definitely~~ needed.

Paragraph beginning at page 2, line 13 has been amended as follows:

Q2 A radiation noise from a semiconductor device increases in proportion to an area of a current loop formed by a circuit being bypassed by a bypass condenser. In the conventional structure of Fig. 1, ~~there is a problem of a low effect in reducing the noise~~ is not effectively reduced because of a relatively large area of a current loop. As shown in Fig.1, the bypass condenser 4 is connected between the power supply terminal and the grounding terminal on the substrate 2. As indicated by an arrow in Fig.1, the current loop includes a circuit, which extends from the power supply terminal to the grounding terminal. Thus, the area of the current loop is large. In addition, a manufacturing cost rises and the number of parts increases ~~since~~ because a separate condenser is attached to the substrate 2 as the bypass condenser 4.

Paragraph beginning at page 2, line 30 has been amended as follows:

Q3 In Fig.2, an area of a current loop is smaller than that shown in Fig.1 because a condenser

is formed within the semiconductor chip 1 so as to be a bypass condenser. The bypass condenser

6 formed within the semiconductor chip 1 is formed by a transistor having a MOS capacity.

A3 Since Because the MOS capacity ~~can not~~ cannot be included in a transistor region, the bypass condenser 6 is needed to be provided in a wiring region or a vacant region within the semiconductor chip 1.

Paragraph beginning at page 3, line 11 has been amended as follows:

A4 In the case of forming a bypass condenser within a semiconductor chip, in chip design step, it is difficult to predict an effect of the bypass condenser. That is, an effective capacity of a bypass condenser and a circuit block, to which the bypass condenser is provided, can not be exactly predicted. The capacity of the bypass condenser to be inserted can be exactly determined by measuring the radiated noise so as to determine which circuit block radiates a large noise, after making a trial semiconductor chip. Accordingly, trial semiconductor chips must be produced several times while changing a position and a capacity of the bypass condenser. Thus, there is a problem in that a long ~~term~~ time is required for developing a semiconductor device.

Paragraph beginning at page 3, line 29 has been amended as follows:

A5 It is a general object of the present invention to provide an improved and ~~an~~ a useful semiconductor device which ~~solve~~ solves the above-mentioned problems.
